



Final Product Change Notification

201810024F01

Issue Date: 19-Nov-2018

Effective Date: 17-Feb-2019

Dear *Gordon Love*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#).



QUALITY

Change Category

Wafer Fab Process

Assembly Process

Product Marking

Test Location

Design

Wafer Fab Materials

Assembly Materials

Mechanical Specification

Test Process

Errata

Wafer Fab Location

Assembly Location
 Other

Packing/Shipping/Labeling

Test Equipment

Electrical spec./Test coverage

Firmware

Substrate Metal Trace Spacing Change at Package Edge for Kinetis K22-120 MHz and K21-120 MHz Devices Assembly in UDG

Description of Change

NXP Semiconductors announces the enlargement of the metal trace from 45 um to 84 um at package edge of Kinetis K22-120 MHz and K21-120 MHz devices assembly in UTAC, Dongguan, China (UDG).

The metal trace enlargement was successfully qualified adhering to NXP specifications.

Please see the attached file(s) for additional details.

Reason for Change

Align the metal trace spacing at package edge with NXP latest guideline. The enlarged spacing has better performance than old spacing.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from 06-Nov-2018

The following sample part number is available:

PK21FN1M0AVMC12

For samples with other part numbers, NXP will deliver within 6 weeks after we receive the request.

Production

Planned first shipment 06-Feb-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 19-Dec-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Fusheng Zhai
Position Product Engineer
e-mail address fusheng.zhai@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.